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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	768B (512 x 12)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c54-rci-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

4.3 External Crystal Oscillator Circuit

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A welldesigned crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 4-3 shows an implementation example of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 k Ω resistor provides the negative feedback for stability. The 10 k Ω potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

FIGURE 4-3: EXAMPLE OF EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT (USING XT, HS OR LP OSCILLATOR MODE)



Figure 4-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The 330 k Ω resistors provide the negative feedback to bias the inverters in their linear region.



PIC16C5X

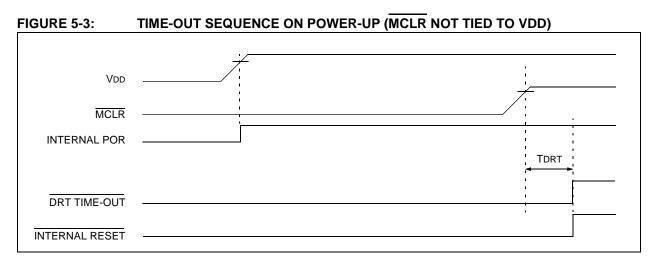


FIGURE 5-4: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): FAST VDD RISE TIME

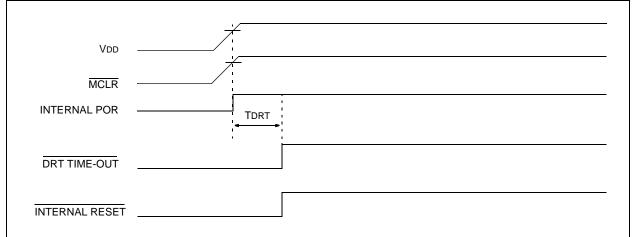
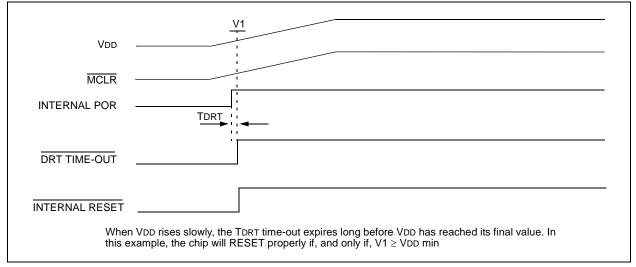


FIGURE 5-5: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): SLOW VDD RISE TIME



NOTES:

CONFIGURATION WORD FOR PIC16C54/C55/C56/C57 **REGISTER 9-2:**

							İ	СР	WDTE	FOSC1	FOSC0
		_	_	_				CP	WDIE	FUSCI	
bit 11											bit 0
bit 11-4:	Unimple	mented	Read as '	0'							
bit 3:	CP: Cod	e protecti	on bit.								
		e protecti									
	0 = Code	e protectio	on on								
bit 2:	WDTE: \	Vatchdog	timer ena	ble bit							
	1 = WDT	enabled									
	0 = WDT	disabled									
bit 1-0:	FOSC1:I	FOSC0: (Oscillator s	election b	oits ⁽²⁾						
	00 = LF	oscillato	or								
	01 = X	T oscillato	or								
		S oscillato									
	11 = R	C oscillate	or								
Note 1.	Refer to t	ha PIC16	C5X Prog	rammina	Specificat	ions (Liter	atura Num	her DS3	190) to d	otormino l	now to
			iration wor	0	opeemear				, 100) to u		1011 10
2:		•	orts XT, R		oscillator	onlv.					
						- 1					
Legend:											

Legend:					
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'			
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown		

Mnemonic, Description		Cualaa	12-Bit Opcode			Status	Nataa	
Opera	nds	Description	Cycles	MSb		LSb	Affected	Notes
ADDWF	f,d	Add W and f	1	0001	11df	ffff	C,DC,Z	1,2,4
ANDWF	f,d	AND W with f	1	0001	01df	ffff	Z	2,4
CLRF	f	Clear f	1	0000	011f	ffff	Z	4
CLRW	-	Clear W	1	0000	0100	0000	Z	
COMF	f, d	Complement f	1	0010	01df	ffff	Z	
DECF	f, d	Decrement f	1	0000	11df	ffff	Z	2,4
DECFSZ	f, d	Decrement f, Skip if 0	1 ⁽²⁾	0010	11df	ffff	None	2,4
INCF	f, d	Increment f	1	0010	10df	ffff	Z	2,4
INCFSZ	f, d	Increment f, Skip if 0	1 ⁽²⁾	0011	11df	ffff	None	2,4
IORWF	f, d	Inclusive OR W with f	1	0001	00df	ffff	Z	2,4
MOVF	f, d	Move f	1	0010	00df	ffff	Z	2,4
MOVWF	f	Move W to f	1	0000	001f	ffff	None	1,4
NOP	-	No Operation	1	0000	0000	0000	None	
RLF	f, d	Rotate left f through Carry	1	0011	01df	ffff	С	2,4
RRF	f, d	Rotate right f through Carry	1	0011	00df	ffff	С	2,4
SUBWF	f, d	Subtract W from f	1	0000	10df	ffff	C,DC,Z	1,2,4
SWAPF	f, d	Swap f	1	0011	10df	ffff	None	2,4
XORWF	f, d	Exclusive OR W with f	1	0001	10df	ffff	Z	2,4
BIT-ORIEN	TED FIL	E REGISTER OPERATIONS	•					
BCF	f, b	Bit Clear f	1	0100	bbbf	ffff	None	2,4
BSF	f, b	Bit Set f	1	0101	bbbf	ffff	None	2,4
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	0110	bbbf	ffff	None	
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	0111	bbbf	ffff	None	
LITERAL A	ND CON	ITROL OPERATIONS	•					
ANDLW	k	AND literal with W	1	1110	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	1001	kkkk	kkkk	None	1
CLRWDT	k	Clear Watchdog Timer	1	0000	0000	0100	TO, PD	
GOTO	k	Unconditional branch	2	101k	kkkk	kkkk	None	
IORLW	k	Inclusive OR Literal with W	1	1101	kkkk	kkkk	Z	
MOVLW	k	Move Literal to W	1	1100	kkkk	kkkk	None	
OPTION	k	Load OPTION register	1	0000	0000	0010	None	
RETLW	k	Return, place Literal in W	2	1000	kkkk	kkkk	None	
SLEEP	_	Go into standby mode	1	0000	0000	0011	TO, PD	
TRIS	f	Load TRIS register	1	0000	0000	Offf	None	3
XORLW	k	Exclusive OR Literal to W	1	1111	kkkk	kkkk	Z	

TABLE 10-2: INSTRUCTION SET SUMMARY

Note 1: The 9th bit of the program counter will be forced to a '0' by any instruction that writes to the PC except for GOTO (see Section 6.5 for more on program counter).

2: When an I/O register is modified as a function of itself (e.g. MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

3: The instruction TRIS f, where f = 5, 6 or 7 causes the contents of the W register to be written to the tristate latches of PORTA, B or C respectively. A '1' forces the pin to a hi-impedance state and disables the output buffers.

4: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared (if assigned to TMR0).

NOTES:

12.4 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial) PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

			$\begin{array}{l} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$				
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions
D030	VIL	Input Low Voltage I/O ports MCLR (Schmitt Trigger) TOCKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1 (Schmitt Trigger)	Vss Vss Vss Vss Vss		0.2 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.3 VDD	>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>>	Pin at hi-impedance PIC16C5X-RC only ⁽³⁾ PIC16C5X-XT, 10, HS, LP
D040	Vih	Input High Voltage I/O ports I/O ports I/O ports MCLR (Schmitt Trigger) TOCKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1 (Schmitt Trigger)	0.45 VDD 2.0 0.36 VDD 0.85 VDD 0.85 VDD 0.85 VDD 0.7 VDD		VDD VDD VDD VDD VDD VDD VDD	> > > > > > > > > > > > > > > > > > > >	For all VDD ⁽⁴⁾ 4.0V < VDD ≤ 5.5V ⁽⁴⁾ VDD > 5.5V PIC16C5X-RC only ⁽³⁾ PIC16C5X-XT, 10, HS, LP
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 VDD*	—	—	V	
D060	Ιι∟	Input Leakage Current ^(1,2) I/O ports MCLR MCLR T0CKI OSC1	-1 -5 -3 -3	0.5 — 0.5 0.5 0.5	+1 +5 +3 +3	μΑ μΑ μΑ μΑ	For VDD \leq 5.5V: VSS \leq VPIN \leq VDD, pin at hi-impedance VPIN = VSS + 0.25V VPIN = VDD VSS \leq VPIN \leq VDD VSS \leq VPIN \leq VDD, PIC16C5X-XT, 10, HS, LP
D080	Vol	Output Low Voltage I/O ports OSC2/CLKOUT		—	0.6 0.6	V V	IOL = 8.7 mA, VDD = 4.5V IOL = 1.6 mA, VDD = 4.5V, PIC16C5X-RC
D090	Vон	Output High Voltage ⁽²⁾ I/O ports OSC2/CLKOUT	Vdd – 0.7 Vdd – 0.7			V V	IOH = -5.4 mA, VDD = 4.5V IOH = -1.0 mA, VDD = 4.5V, PIC16C5X-RC

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

- **Note 1:** The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.
 - 2: Negative current is defined as coming out of the pin.
 - **3:** For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.
 - 4: The user may use the better of the two specifications.

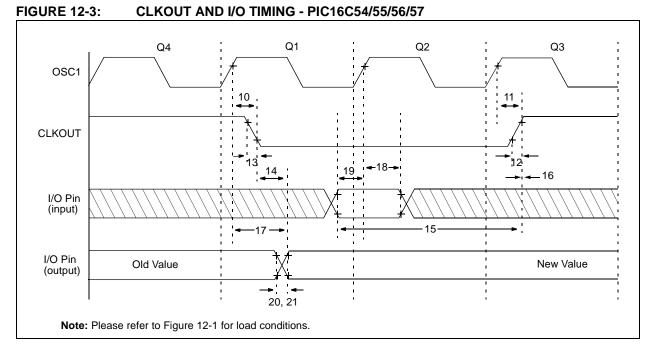


TABLE 12-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C54/55/56/57

AC Char	acteristics	$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \end{array}$							
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units			
10	TosH2ckL	OSC1↑ to CLKOUT↓ ⁽¹⁾	_	15	30**	ns			
11	TosH2ckH	OSC1↑ to CLKOUT↑ ⁽¹⁾	_	15	30**	ns			
12	TckR	CLKOUT rise time ⁽¹⁾		5.0	15**	ns			
13	TckF	CLKOUT fall time ⁽¹⁾	—	5.0	15**	ns			
14	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾			40**	ns			
15	TioV2ckH	Port in valid before CLKOUT ⁽¹⁾	0.25 TCY+30*	_	_	ns			
16	TckH2iol	Port in hold after CLKOUT ⁽¹⁾	0*	_	_	ns			
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid ⁽²⁾	_		100*	ns			
18	TosH2iol	OSC1 [↑] (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—		ns			
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns			
20	TioR	Port output rise time ⁽²⁾	—	10	25**	ns			
21	TioF	Port output fall time ⁽²⁾	—	10	25**	ns			

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Please refer to Figure 12-1 for load conditions.

13.1 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

PIC16LCR54A-04 PIC16LCR54A-04I (Commercial, Industrial)				$\begin{tabular}{lllllllllllllllllllllllllllllllllll$					
PIC16CR54A-04, 10, 20 PIC16CR54A-04I, 10I, 20I (Commercial, Industrial)			$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$						
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions		
	IPD	Power-down Current ⁽²⁾							
D006		PIC16LCR54A-Commercial		1.0 2.0 3.0 5.0	6.0 8.0* 15 25	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled		
D006A		PIC16CR54A-Commercial		1.0 2.0 3.0 5.0	6.0 8.0* 15 25	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled		
D007		PIC16LCR54A-Industrial		1.0 2.0 3.0 3.0 5.0	8.0 10* 20* 18 45	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 4.0V, WDT enabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled		
D007A		PIC16CR54A-Industrial		1.0 2.0 3.0 3.0 5.0	8.0 10* 20* 18 45	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 4.0V, WDT enabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled		

Legend: Rows with standard voltage device data only are shaded for improved readability.

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.
- **Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k Ω .

14.0 DEVICE CHARACTERIZATION - PIC16C54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is a standard deviation, over the whole temperature range.



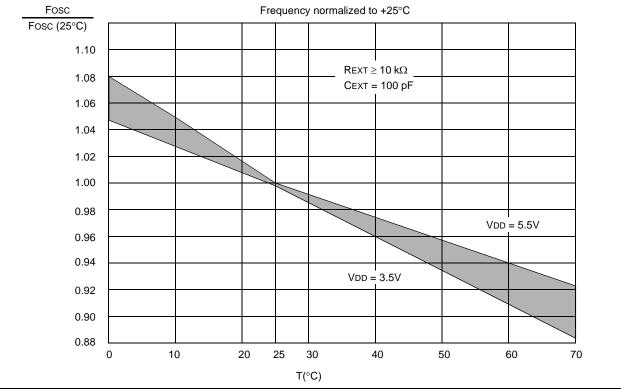


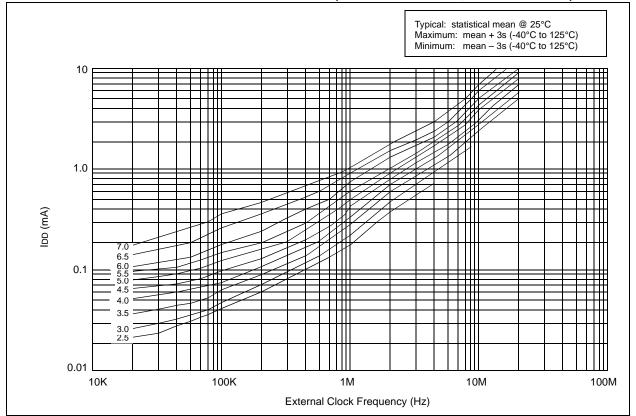
TABLE 14-1: RC OSCILLATOR FREQUENCIES

Сехт	Rext	Average Fosc @ 5 V, 25°C				
20 pF	3.3K	5 MHz	± 27%			
	5K	3.8 MHz	± 21%			
	10K	2.2 MHz	± 21%			
	100K	262 kHz	± 31%			
100 pF	3.3K	1.6 MHz	± 13%			
	5K	1.2 MHz	± 13%			
	10K	684 kHz	± 18%			
	100K	71 kHz	± 25%			
300 pF	3.3K	660 kHz	± 10%			
	5.0K	484 kHz	± 14%			
	10K	267 kHz	± 15%			
	100K	29 kHz	± 19%			

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ± 3 standard deviations from the average value for VDD = 5V.







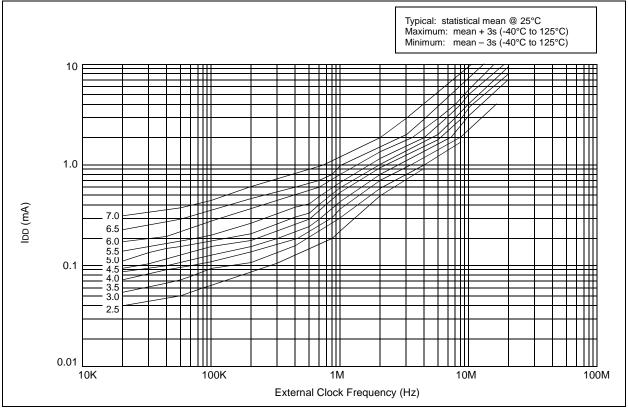




TABLE 16-2:INPUT CAPACITANCE FOR
PIC16C54A/C58A

Pin	Typical Capacitance (pF)				
FIII	18L PDIP	18L SOIC			
RA port	5.0	4.3			
RB port	5.0	4.3			
MCLR	17.0	17.0			
OSC1	4.0	3.5			
OSC2/CLKOUT	4.3	3.5			
TOCKI	3.2	2.8			

All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

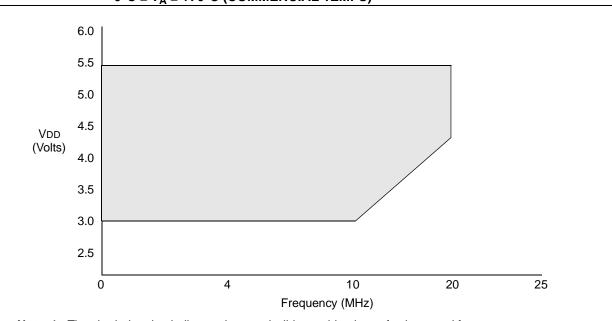
FIGURE 16-23: PORTA, B AND C IOL vs. VOL, VDD = 5V



NOTES:

PIC16C5X

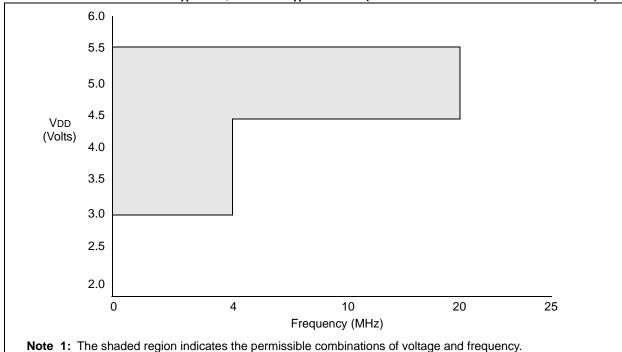






2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.





2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency.

Please reference the Product Identification System section for the maximum rated speed of the parts.

TABLE 17-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics		$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \end{array}$					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
2	Тсу	Instruction Cycle Time ⁽²⁾	—	4/Fosc		—	
3	TosL, TosH	Clock in (OSC1) Low or High Time	50* 20*			ns ns	XT oscillator HS oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	2.0*	_	 25*	μS ns	LP oscillator XT oscillator
			_		25* 50*	ns ns	HS oscillator LP oscillator

- * These parameters are characterized but not tested.
- † Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- **Note 1:** All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.









FIGURE 20-4: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF I/O PINS vs. VDD

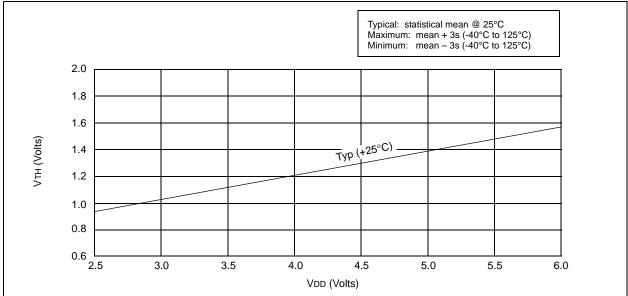
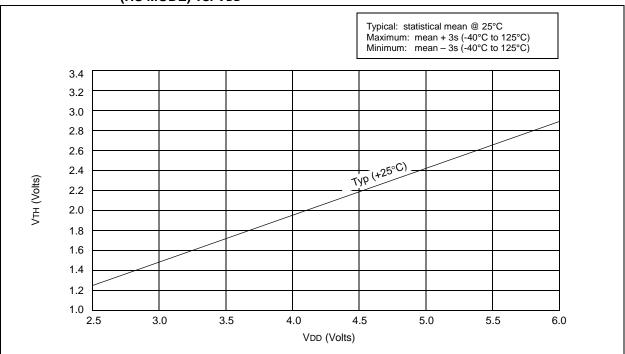


FIGURE 20-5: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF OSC1 INPUT (HS MODE) vs. VDD

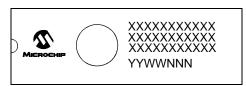


Package Marking Information (Cont'd)

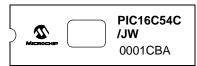
18-Lead CERDIP Windowed

	XXXXXXXX XXXXXXXX YYWWNNN
--	---------------------------------

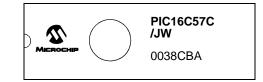
28-Lead CERDIP Windowed



Example



Example



Lege	end: XX? Y YY WW NNN @3 *	 Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note	be carr	vent the full Microchip part number cannot be marked on one line, it will ied over to the next line, thus limiting the number of available ers for customer-specific information.

28-Lead Plastic Dual In-line (P) - 600 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	Jnits INCHES*			MILLIMETERS		
Dimer	ision Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	А	.160	.175	.190	4.06	4.45	4.83
Molded Package Thickness	A2	.140	.150	.160	3.56	3.81	4.06
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Molded Package Width	E1	.505	.545	.560	12.83	13.84	14.22
Overall Length	D	1.395	1.430	1.465	35.43	36.32	37.21
Tip to Seating Plane	L	.120	.130	.135	3.05	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.030	.050	.070	0.76	1.27	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.620	.650	.680	15.75	16.51	17.27
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-011 Drawing No. C04-079

ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web (WWW) site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape or Microsoft Explorer. Files are also available for FTP download from our FTP site.

Connecting to the Microchip Internet Web Site

The Microchip web site is available by using your favorite Internet browser to attach to:

www.microchip.com

The file transfer site is available by using an FTP service to connect to:

ftp://ftp.microchip.com

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

- Latest Microchip Press Releases
- Technical Support Section with Frequently Asked Questions
- Design Tips
- Device Errata
- Job Postings
- Microchip Consultant Program Member Listing
- Links to other useful web sites related to Microchip Products
- Conferences for products, Development Systems, technical information and more
- Listing of seminars and events